ASSOCIATION ELECTRONIC	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.											
1752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater						als and Mfg Information				
Supplier	· Information															
Company name* Company unique ID				ique ID	Uniq			Unique ID Authority					Response Date*			
nsemi													2023-06-08			
Contact Name Title - Con				intact			Phone - Contact*					Email - Contact*				
Product-Env-Stewards Produ				Product Enviro Compliance			NA					Product-Env-Stewards@onsemi.com				
Authorized Representative*  Title - Representative				sentative	ative P		Phone - Repi	hone - Representative*				Email - Representative*				
Product-E	Env-Stewards	Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com					
	Requester Item Number Mfr Item		n Number Mfr Item Name				Effective Date Version Manufacturin		uring Site	Weight*		*	UOM	Unit Type		
		NSPU5221MUTBG 22V UNIDIRECTION PROTECTION		ONAL SUR	GE	2023-06-08	PHM			5	5.52		mg	Each		
<b>Aanufa</b>	cturing Proccess Informa	ation														
	Terminal Plating / Grid Array Material Terminal			minal Base Alloy J-STD-020 MSL Ra			ng Peak Process Body Temperature Max Time at Peak					Temperat	ure N	Number of	Reflow Cyc	les
Matte Tin (Sn) - annealed CU Alloy			1			260		C	30		secon	ds 3				
Comments																
evel 1 - ma	aximum time at peak temperat	ure during sol	dering is 10-3	0 seconds												
or more i	information regarding materia	l composition	please refer to	page 3												

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its uppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

<b>Homogeneous Material</b>	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.49	mg	Supplier	Silicon (Si)	7440-21-3		0.49	mg
Die Attach	0.2	mg		Epoxy resin	proprietary data		0.03	mg
			Supplier	Silver (Ag)	7440-22-4		0.16	mg
			Supplier	Bismaleimide	13676-54-5		0.01	mg
Lead Frame	2.13	mg	Supplier	Silver (Ag)	7440-22-4		0.0213	mg
			Supplier	Tin (Sn)	7440-31-5		0.0053	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0047	mg
			Supplier	Chromium (Cr)	7440-47-3		0.0053	mg
			Supplier	Copper (Cu)	7440-50-8		2.0934	mg
Mold Compound-Black	2.55	mg		Epoxy resin	proprietary data		0.1198	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.255	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0026	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		2.0527	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.1198	mg
Plating	0.11	mg	Supplier	Tin (Sn)	7440-31-5		0.11	mg
Wire Bond	0.04	mg	Supplier	Palladium (Pd)	7440-05-3		0.0004	mg
			Supplier	Copper (Cu)	7440-50-8		0.0396	mg